



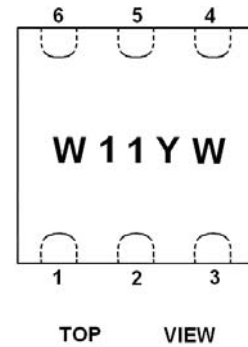
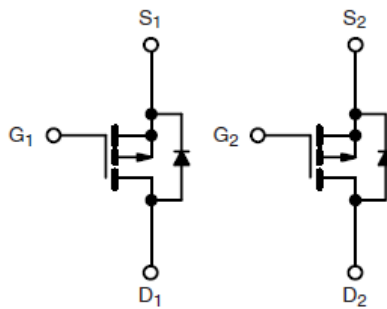
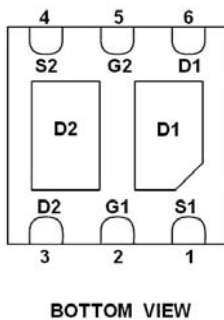
## General Description

AFP2911W, P-Channel enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent  $R_{DS(ON)}$ , low gate charge. These devices are particularly suited for low voltage power management, such as smart phone and notebook computer and other battery powered circuits, and low in-line power loss are needed in commercial industrial surface mount applications.

## Features

- -20V/-4.5A,  $R_{DS(ON)}=80m\Omega@V_{GS}=-4.5V$
- -20V/-3.8A,  $R_{DS(ON)}=105m\Omega@V_{GS}=-2.5V$
- -20V/-2.5A,  $R_{DS(ON)}=145m\Omega@V_{GS}=-1.8V$
- Super high density cell design for extremely low  $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- DFN2X2-6L package design

## Pin Description ( DFN2X2-6L )



## Application

- Load Switch
- Portable Equipment
- Battery Powered System

## Pin Define

Pin	Symbol	Description
1	S1	Source1
2	G1	Gate1
3	D2	Drain2
4	S2	Source2
5	G2	Gate2
6	D1	Drain1

## Ordering Information

Part Ordering No.	Part Marking	Package	Unit	Quantity
AFP2911WFN226RG	W11YW	DFN2X2-6L	Tape & Reel	4000 EA

- ※ W11 parts code
- ※ Y year code
- ※ W week code ( A ~ Z = 1 ~ 26 / a ~ z = 27 ~ 52 )
- ※ AFP2911WFN226RG : 7" Tape & Reel ; Pb- Free ; Halogen -Free



**Absolute Maximum Ratings**

(T<sub>A</sub>=25°C Unless otherwise noted)

Parameter	Symbol	Typical	Unit
Drain-Source Voltage	V <sub>DSS</sub>	-20	V
Gate –Source Voltage	V <sub>GSS</sub>	±12	V
Continuous Drain Current(T <sub>J</sub> =150°C)	I <sub>D</sub>	T <sub>A</sub> =25°C	-4.5
		T <sub>A</sub> =70°C	-3.8
Pulsed Drain Current	I <sub>DM</sub>	-12	A
Continuous Source Current(Diode Conduction)	I <sub>S</sub>	-1.6	A
Power Dissipation	P <sub>D</sub>	T <sub>A</sub> =25°C	6.5
		T <sub>A</sub> =70°C	4.2
Operating Junction Temperature	T <sub>J</sub>	150	°C
Storage Temperature Range	T <sub>STG</sub>	-55/150	°C
Thermal Resistance-Junction to Ambient	R <sub>θJA</sub>	120	°C/W

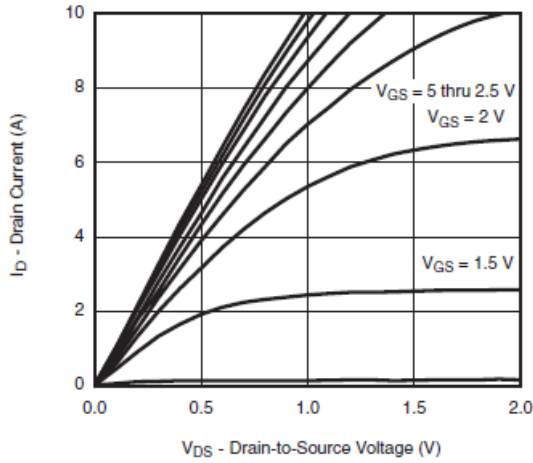
**Electrical Characteristics**

(T<sub>A</sub>=25°C Unless otherwise noted)

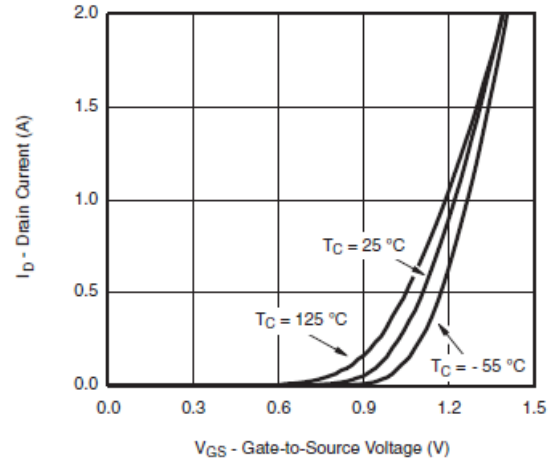
Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =-250uA	-20			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250uA	-0.3		-0.8	
Gate Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±12V			±100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-16V, V <sub>GS</sub> =0V			-1	uA
		V <sub>DS</sub> =-16V, V <sub>GS</sub> =0V T <sub>J</sub> =85°C			-30	
On-State Drain Current	I <sub>D(on)</sub>	V <sub>DS</sub> ≤ -5V, V <sub>GS</sub> =-4.5V	-8			A
		V <sub>DS</sub> ≤ -5V, V <sub>GS</sub> =-2.5V	-3			
Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-4.5A		60	80	mΩ
		V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-3.8A		80	105	
		V <sub>GS</sub> =-1.8V, I <sub>D</sub> =-2.5A		115	145	
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =-5V, I <sub>D</sub> =-2.8A		6.5		S
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =-1.25A, V <sub>GS</sub> =0V		-0.75	-1.3	V
<b>Dynamic</b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =-10V, V <sub>GS</sub> =-4.5V I <sub>D</sub> =-3.5A		5	10	nC
Gate-Source Charge	Q <sub>gs</sub>			0.85		
Gate-Drain Charge	Q <sub>gd</sub>			1.5		
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =-10V, V <sub>GS</sub> =0V f=1MHz		375		pF
Output Capacitance	C <sub>oss</sub>			80		
Reverse Transfer Capacitance	C <sub>rss</sub>			60		
Turn-On Time	t <sub>d(on)</sub>	V <sub>DD</sub> =-10V, R <sub>L</sub> =2.85Ω I <sub>D</sub> =-3.5A, V <sub>GEN</sub> =-4.5V R <sub>G</sub> =1Ω		15	25	ns
	t <sub>r</sub>			36	60	
Turn-Off Time	t <sub>d(off)</sub>			25	50	
	t <sub>f</sub>			15	25	



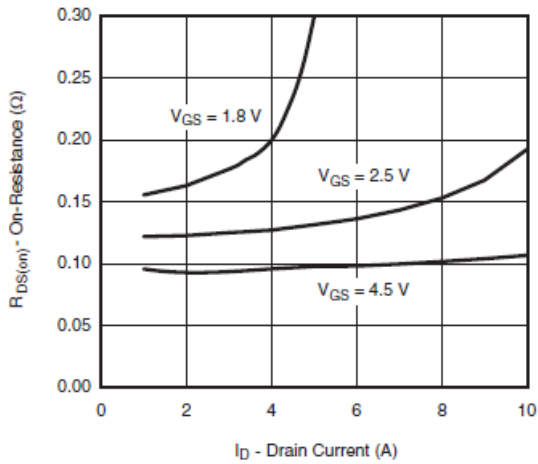
## Typical Characteristics



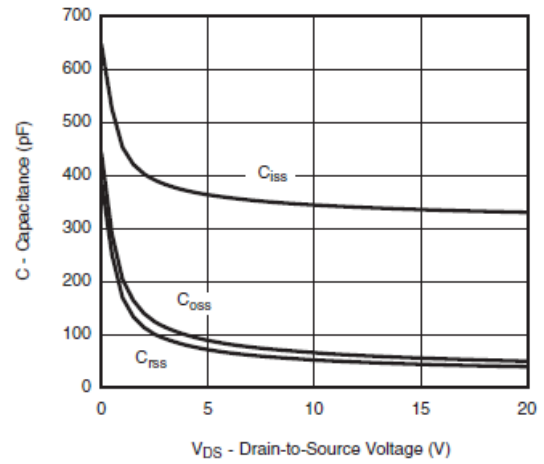
Output Characteristics



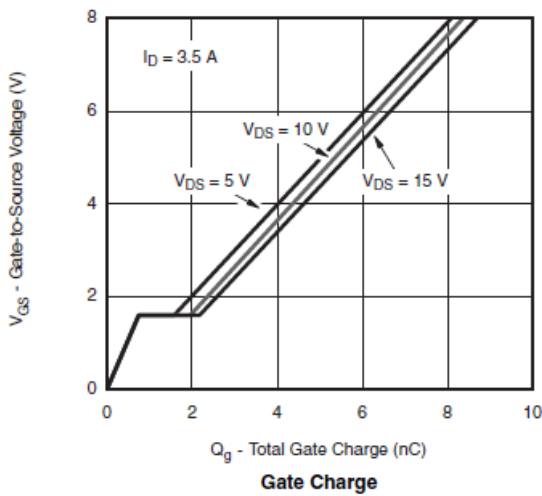
Transfer Characteristics



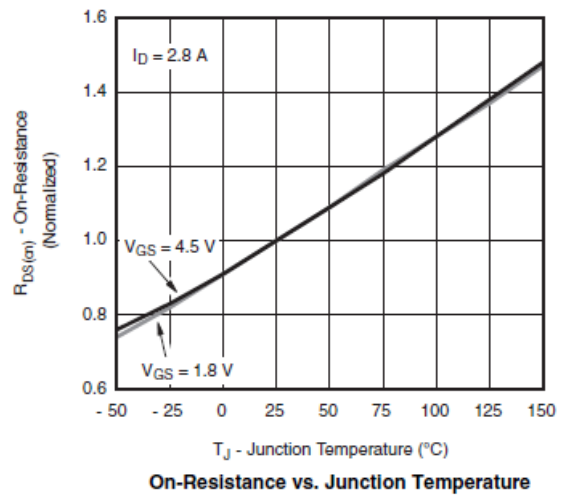
On-Resistance vs. Drain Current and Gate Voltage



Capacitance



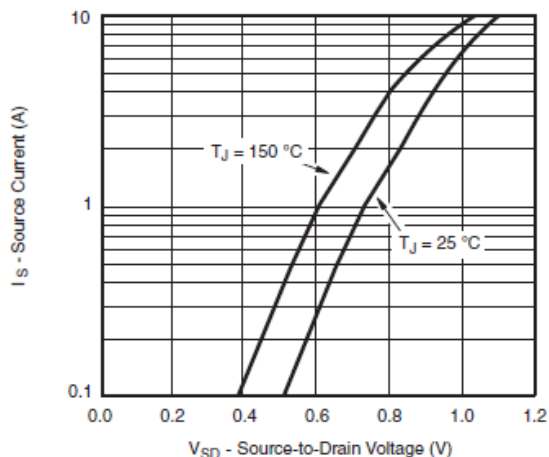
Gate Charge



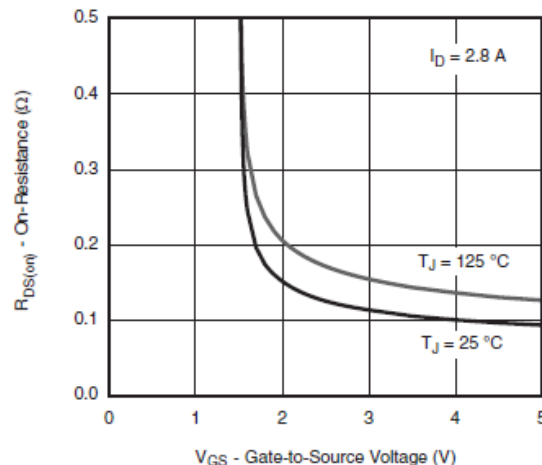
On-Resistance vs. Junction Temperature



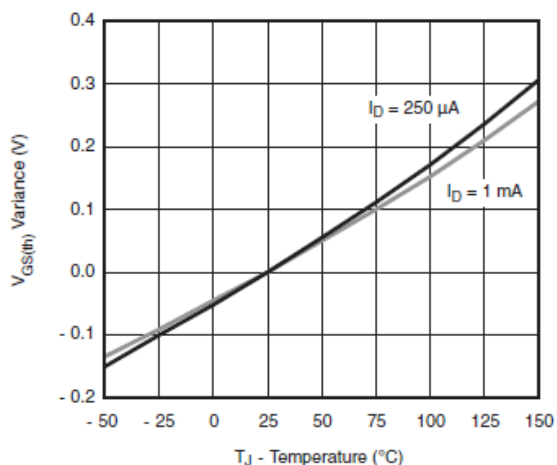
## Typical Characteristics



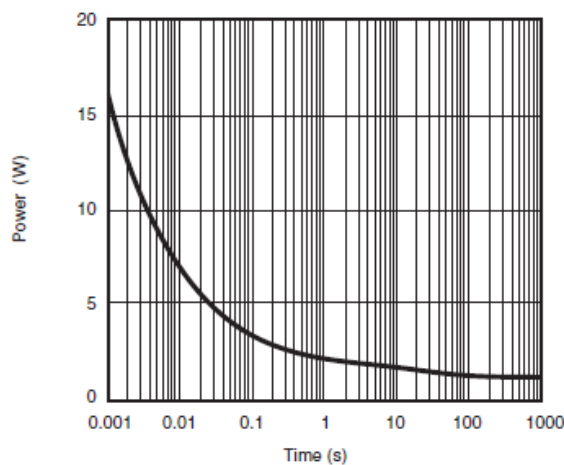
Source-Drain Diode Forward Voltage



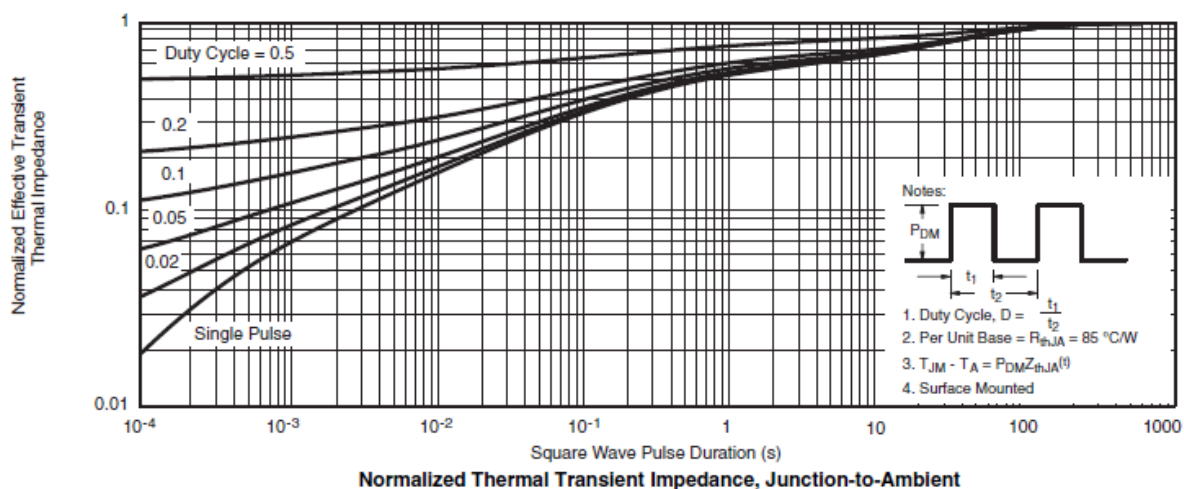
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



Single Pulse Power, Junction-to-Ambient

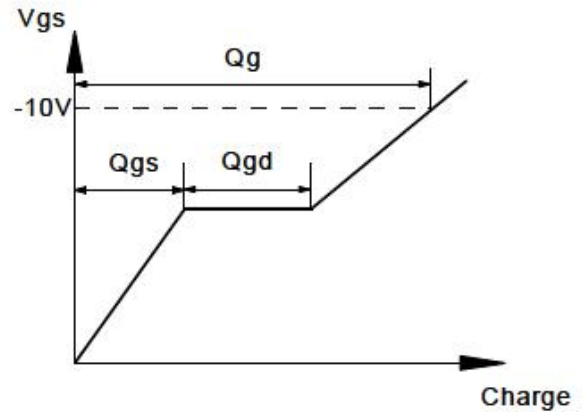
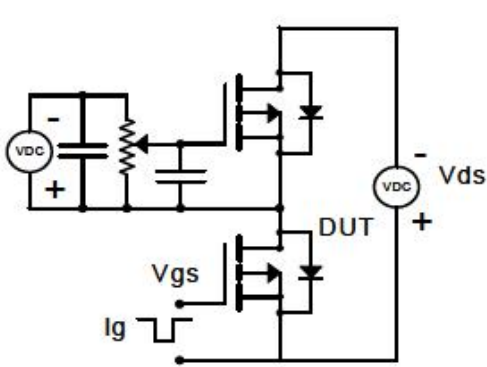


Normalized Thermal Transient Impedance, Junction-to-Ambient

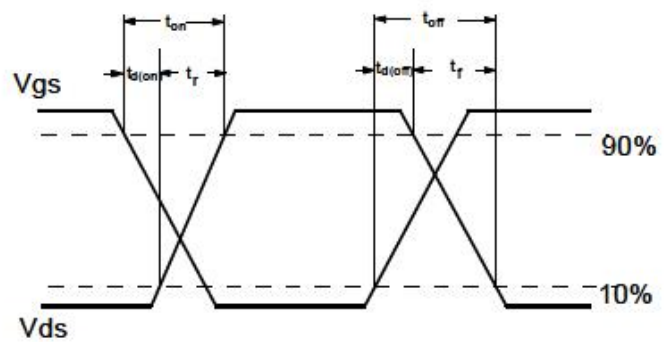
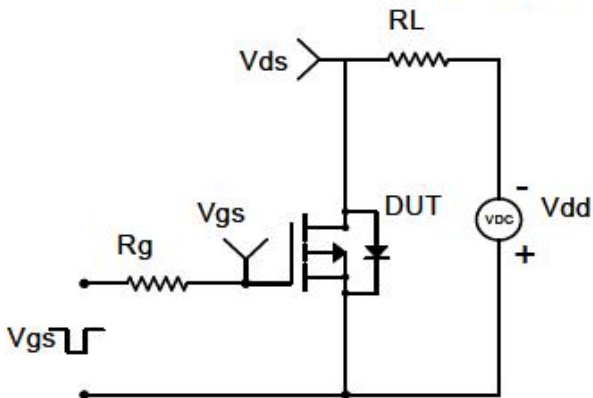


## Typical Characteristics

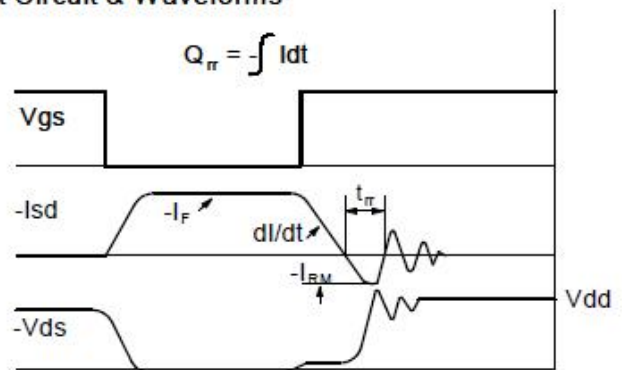
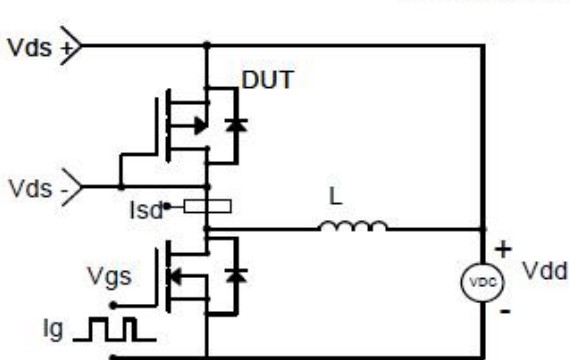
### Gate Charge Test Circuit & Waveform



### Resistive Switching Test Circuit & Waveforms

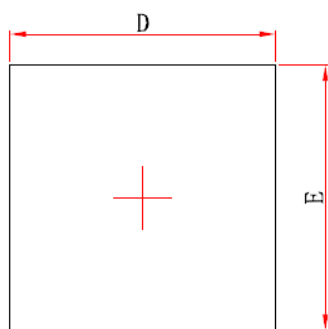


### Diode Recovery Test Circuit & Waveforms

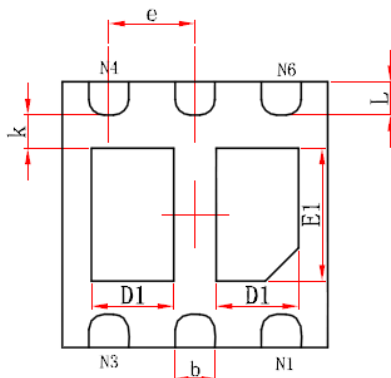




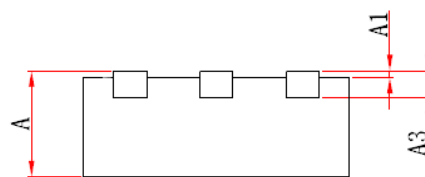
**Package Information ( DFN2X2-6L )**



**Top View**



**Bottom View**



**Side View**

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700	0.800	0.028	0.031
A1	0.000	0.050	0.000	0.002
A3	0.203REF.		0.008REF.	
D	1.924	2.076	0.076	0.082
E	2.924	3.076	0.115	0.121
D1	1.400	1.600	0.055	0.063
E1	1.400	1.600	0.055	0.063
k	0.200MIN.		0.008MIN.	
b	0.200	0.300	0.008	0.012
e	0.500TYP.		0.020TYP.	
L	0.224	0.376	0.009	0.015

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 2F, No.80, Sec.1, Cheng Kung Rd., Nan Kang Dist., Taipei City 115, Taiwan (R.O.C.)  
 Tel : 886 2) 2651 3928  
 Fax : 886 2) 2786 8483  
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